

Day 1 - Monday 20th April 2026

11:00 AngelTech Innovate Summit - Limited places! Requires separate registration: <https://www.angeltech-innovate.net/register>

18:00 Pre-conference Networking Drinks / Dinner Reception (available to those who have registered for 21st & 22nd April for AngelTech Conference)

Day 2 - Tuesday 21st April 2026

08:00 Registration and welcome refreshments

08:50 Housekeeping by Conference Chair

Heterogeneous Integration

09:00 **Silicon to Systems: How Advanced Packaging Is Redefining Performance Scaling**

Presented by Diana Khlan - Chips Weekly

09:20 **Bridging the Gap: Collaborative Industry - Research Ecosystems in Advanced Packaging**

Presented by Ulrike Ganesh - Fraunhofer IZM

09:40 **Sub-Micron Active Alignment: Enabling Advanced Packaging at the Nanometer Level**

Presented by David Forer - Physik

10:00 **Heterogeneous Integration and Co-packaged Optics: Meeting AI Bandwidth Demand**

Presented by Himani Suhag Kamineni - GlobalFoundries

10:20 **Advanced Photonic Assembly for Co-Packaged Optics**

Presented by Bert Offrein - IBM

10:40 Morning Break - Refreshments & Networking

11:10 **Foundry 2.0: A New Foundation for Semiconductors and Innovation**

Presented by Robert Patti - NHanced Semiconductors

Localized Electrochemical Manufacturing (LEM): A Scalable High-Density Interconnect Platform for Next-Generation

11:30 **Heterogeneous Integration**

Presented by Sebastiaan Muller - Syenta

11:50 **Thin Film Deposition Developments for Large Size Packages on Panel Scale**

Presented by Andre Schenk - Evatec

12:10 **From Innovation to High-Volume Production: Scaling Heterogeneous Integration and Co-Packaged Optics**

Presented by Anneirudh Sundararajan - PHIX Photonics Assembly

12:30 Lunch Break, Networking & Posters

Manufacturing & Pilot Lines

14:00 **Supporting the European Advanced Packaging Ecosystem in HVM and Innovation**

Presented by Eoin O'Toole - Amkor Technology

14:20 **Process Integration in Redistribution Layer Manufacturing**

Presented by Bernhard Hammerl - Siconnex

14:40 **Assembly Design Kit Challenges and Opportunities**

Presented by David Harame - AIM Photonics

15:00 **APECS Pilot Line: Shaping the Future of Heterogeneous Integration and Advanced Packaging**

Presented by Johannes Rittner - FMD / APECS

15:20 **Advanced Photonics Packaging in the AI Era**

Presented by Massimo Leo - Jabil

15:40 Afternoon Break and Networking

Materials, Design and Reliability

16:10 **The European Chip Design Platform (EuroCDP): Enabling Access to Advanced Semiconductor Design in Europe**

Presented by Helio Fernandez Tellez - imec

16:30 **From Miniaturization to System Integration: The Growing Role of Semiconductor Packaging**

Presented by Dr. Pascal Oberndorff - NXP Semiconductors

16:50 **Next-Generation Silicon Photonics Platforms Enabled by Micro-Transfer Printing – The TRANSVERSE Pilot Line**

Presented by Gunther Roelkens - Ghent University - imec

17:10 **Design Enablement of a Heterogeneously Integrated Electronic-Photonic System in a Package**

Presented by Sylwester Latkowski - PITC

17:30 **Packaging Reliability for Space and High Reliability Environments**

Presented by Finbarr Waldron - Tyndall National Institute

17:50 Closing Remarks

18:00 Networking Drinks and Dinner Reception (concludes around 20:00)

18:30 **AngelTech Rump Session - Bottlenecks & Battlegrounds: The Future of the AI Chip Ecosystem**

Presented by David Cheskis - Square Zero Technologies, and Diana Khlan - Chips Weekly

Day 3 - Wednesday 22nd April 2026

08:00 Registration and welcome refreshments

08:50 Housekeeping by Conference Chair

Advancing Thermal Management

09:00 **Beating the Heat: Diamond as an Enabler for High-Performance Advanced Packages**

Presented by Joana Mendes - Instituto de Telecomunicações

09:20 **Advanced Thermal Management in High-Power Electronics Packaging Using Metal-Diamond Composite Heat Spreaders**

Presented by Zeina Abdallah - University of Bristol

09:40 **Direct Atomic Layer Processing (DALP®): Spatially Localized, Multi-Material Fabrication for Next-Generation Devices from Discovery to Manufacturing**

Presented by Mira Baraket - ATLANT 3D

Getting the Best Out of Incumbent Solutions

10:00 **From Capability to Scale: Accelerating the Advanced Packaging Ecosystem**

Presented by Dr Gladys Benghalia - National Advanced Semiconductor Packaging and Integration Centre (NASPIC)

10:20 **Beyond the Mask: Multibeam Laser Lithography for Cost-effective, Flexible, and High-Precision Advanced Packaging**

Presented by Sander Schellingerhout - Raith

10:40 **Optimising Legacy Wet Strip for Advanced Packaging**

Presented by Phillip Sundin - SHELLBACK Semiconductor Technology

11:00 Morning Break and Networking

11:30 **Beyond the Standard: Redefining Semiconductor Packaging as a Specialized OSAT**

Presented by Daniel Lieske - AEMtec

11:50 **Medium Volume Production and Advanced Packaging in the UK**

Presented by John Boston - Custom Interconnect

12:10 **Photonics Packaging Moving Toward Scalability for a Fast-growing Market**

Presented by Eric Mounier - Yole Group

12:30 Lunch Break, Networking & Posters

Optimising Packaging Architectures

13:40 **Recent Developments in Advanced Heterogeneous 3D Integration at the Wafer Level**

Presented by Jean-Charles Souriau - CEA Leti

14:00 **Photonic Wire Bonds and Facet-Attached Micro-Lenses: Enabling Scalable Integration of Lasers and PICs**

Presented by Laura Horan - Vanguard Automation

14:20 **Advanced Metrology for the Challenges of Advanced Packaging**

Presented by Simon Cannonier - cyberTECHNOLOGIES

14:40 **A Sustainable Dicing Innovation for Cutting-Edge Semiconductor Challenges**

Presented by Christian Keil - Lidrotec GmbH

15:00 Afternoon Coffee Break

15:30 **Advanced Packaging Methods for Heterogeneous Integration**

Presented by Travis Scott - Finetech GmbH

15:50 **Digital Coating: Scalable and Material Saving Material Deposition**

Presented by David Volk - SUSS Micro Tec

16:10 **Accelerating the Future: Enabling the Next Era of Advanced Integration with Multibeam- High-Productivity E-Beam**

Lithography

Presented by Ken MacWilliams - Multibeam

16:30 **Eliminating Sub-Micron Alignment: Self-Aligned Cantilever Packaging for Scalable Silicon Photonics**

Presented by Paul Marchal - Photon Bridge

16:50 Closing Remarks

